



Final Product/Process Change Notification

Document #:FPCN26917XA

Issue Date:07 May 2026

Title of Change:	Addition of Manufacturing Site and Wafer Size for T10-80V MOSFET Technology at onsemi East Fishkill, United States
Proposed First Ship date:	14 Aug 2026 or earlier if approved by customer
Contact Information:	Contact your local onsemi Sales Office
PCN Samples Contact:	Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.
Additional Reliability Data:	Contact your local onsemi Sales Office
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. onsemi will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com
Marking of Parts/ Traceability of Change:	Changed material can be identified by assembly plant code
Change Category:	Wafer Fab Change, Test Change, Assembly Change
Change Sub-Category(s):	Addition of 12-inch wafers from EFK, Manufacturing Site Addition

Sites Affected:

onsemi Sites	External Foundry/Subcon Sites
onsemi Seremban, Malaysia	AMKOR, Malaysia
onsemi, East Fishkill	

Description and Purpose:

onsemi wishes to inform customers of its plan to add an additional manufacturing site and wafer size for its T10 80-volt MOSFET technology products. This change is intended to support additional manufacturing capacity and supply continuity by qualifying onsemi East Fishkill, New York, United States as an additional site for wafer fabrication, wafer probe, and backgrind and backmetal processing. As part of this change, 300-millimeter wafer manufacturing will be added while maintaining the existing 200-millimeter wafer process.

In addition, a molding compound change at the external assembly site is included.

There are no changes to electrical characteristics or part numbers as a result of this change.

	Before	After
Wafer fabrication site	onsemi Aizu, Japan	onsemi Aizu, Japan onsemi East Fishkill ,US
Wafer size	200mm	200mm 300mm
Wafer probe site	onsemi Seremban, Malaysia	onsemi Seremban, Malaysia onsemi East Fishkill ,US
Backgrind Backmetal site	onsemi Seremban, Malaysia	onsemi Seremban, Malaysia onsemi East Fishkill ,US
Molding Compound	onsemi Seremban - G700LA AMKOR – G700LS	onsemi Seremban - G700LA AMKOR – G700LA



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Qualification Plan:

QV DEVICE NAME NVMFWS1D5N08XT1G

RMS: 104680

PACKAGE: S08FL

Test	Specification	Condition	Interval	Result
High Temperature Reverse Bias	JESD22-A108	Ta= _175_ °C, _100_ % max rated V	1008 hrs	0/231
High Temperature Gate Bias	JESD22-A108	Ta= _175_ °C, 100% max rated Vgss	1008 hrs	0/231
High Temperature Storage Life	JESD22-A103	Ta= 175C	1008 hrs	0/231
Preconditioning	J-STD-020 JESD-A113	MSL 1 @ 260 °C, Pre IOL, TC, uHAST, HAST		0/924
Intermittent Operating Life	MIL-STD-750 (M1037) AEC-Q101	Ta=+25°C, delta Tj=100°C On/off = 2 min	15000 cyc	0/231
Temperature Cycling	JESD22-A104	Ta= -55°C to +150°C	1000 cyc	0/231
Highly Accelerated Stress Test	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs	0/231
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/231

QV DEVICE NAME NVMFWS1D9N08XT1G

RMS: 106247

PACKAGE: S08FL

Test	Specification	Condition	Interval	Result
High Temperature Reverse Bias	JESD22-A108	Ta= _175_ °C, _100_ % max rated V	1008 hrs	0/231
High Temperature Gate Bias	JESD22-A108	Ta= _175_ °C, 100% max rated Vgss	1008 hrs	0/231
High Temperature Storage Life	JESD22-A103	Ta= 175C	1008 hrs	0/231
Preconditioning	J-STD-020 JESD-A113	MSL 1 @ 260 °C, Pre IOL, TC, uHAST, HAST		0/924
Intermittent Operating Life	MIL-STD-750 (M1037) AEC-Q101	Ta=+25°C, delta Tj=100°C On/off = 2 min	15000 cyc	0/231
Temperature Cycling	JESD22-A104	Ta= -55°C to +150°C	1000 cyc	0/231
Highly Accelerated Stress Test	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs	0/231
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/231

Electrical Characteristics Summary:

Electrical characteristics are not impacted.



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List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.

Current Part Number	New Part Number	Qualification Vehicle
NTMFS2D1N08XT1G	#NONE	NVMFWS1D9N08XT1G

PCN Product List Addendum for:

Customer Contact Name: Premier Farnell Dropbox

Customer Contact Email: productchangenotices@newark.com

Appendix A: Changed Products

PCN#: FPCN26917XA
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NWKC: PREMIER FARNELL

Product	Customer Part Number	Qualification Vehicle	New Part Number	Replacement Supplier
NTMFS2D1N08XT1G	4381417	NVMFWS1D9N08XT1G	#NONE	